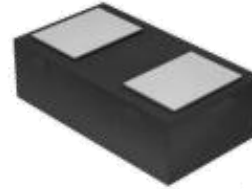


## 1. Features

- Ultra Low Capacitance: 0.35pF(typ.)
- Reverse Working Voltage: 5V
- IEC 61000-4-2 (ESD Air):  $\pm 20$ kV  
IEC 61000-4-2 (ESD Contact):  $\pm 20$ kV  
IEC 61000-4-5 (Lightning 8/20 $\mu$ s): 4.5A

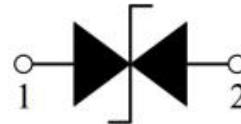
## 2. Pin Description



## 3. Applications

- Smart Phone and Tablet PC
- TV and Set Top Box
- Wearable Devices
- PDA

## 4. Schematic Diagram



## 5. Order Information

Type	Package	Size (mm)	Delivery Form	Delivery Quantity
SLESELCAB5VB	DFN1006	1.00x0.60x0.37	7" T&R	10,000

## 6. Limiting Values( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{ESD}$	Electrostatic Discharge Voltage	IEC 61000-4-2; Contact Discharge	-	$\pm 20$	kV
		IEC 61000-4-2; Air Discharge	-	$\pm 20$	kV
$P_{PP}$	Peak Pulse Power	$t_P = 8/20\ \mu\text{s}$	-	100	W
$I_{PPM}$	Rated Peak Pulse Current	$t_P = 8/20\ \mu\text{s}$	-	4.5	A
$T_A$	Operating Temperature Range	-	-55	125	$^\circ\text{C}$
$T_{stg}$	Storage Temperature Range	-	-55	150	$^\circ\text{C}$

## 7. Electrical Characteristics ( $T_A = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min	Typ.	Max	Unit
$V_{RWM}$	Reverse Working Voltage	$T_A = 25^\circ\text{C}$	-	-	5.0	V
$V_{BR}$	Breakdown Voltage	$I_R = 1\text{mA}; T_A = 25^\circ\text{C}$	6.0	8.5	9.5	V
$I_R$	Reverse Leakage Current	$V_{RWM} = 5\text{V}; T_A = 25^\circ\text{C}$	-	-	0.1	$\mu\text{A}$
$V_C$	Clamping Voltage	$I_{PP} = 1\text{A}, t_p = 8/20\mu\text{s}$	-	-	11	V
		$I_{PP} = 4.5\text{A}, t_p = 8/20\mu\text{s}$	-	-	22	V
$C_J$	Junction Capacitance	$V_R = 0\text{V}, f = 1\text{MHz}$	-	0.35	0.45	pF

## 8. Typical Characteristics

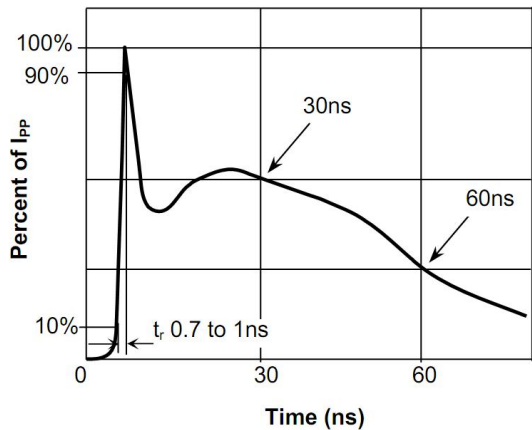


Fig.1 Pulse Waveform-ESD (IEC61000-4-2)

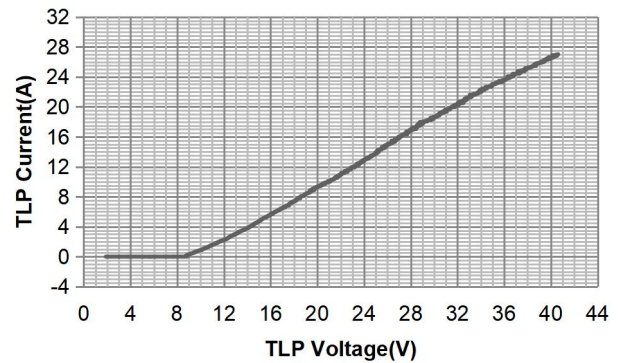


Fig.2 Transmission Line Pulse (TLP)

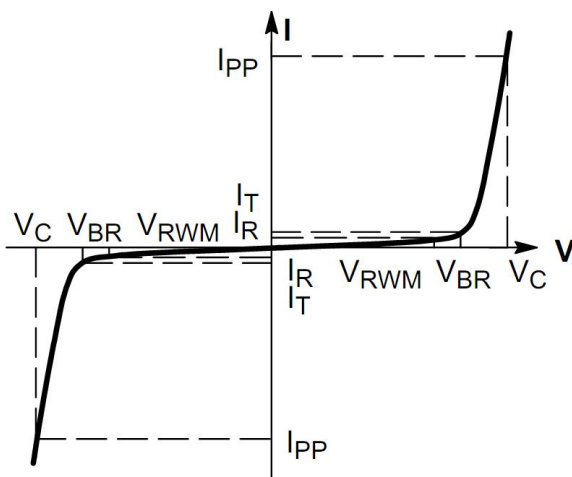


Fig.3 V-I Characteristics for Bidirectional Diode

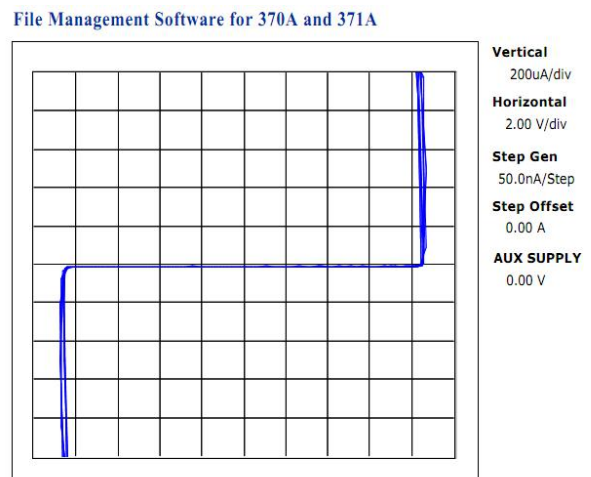
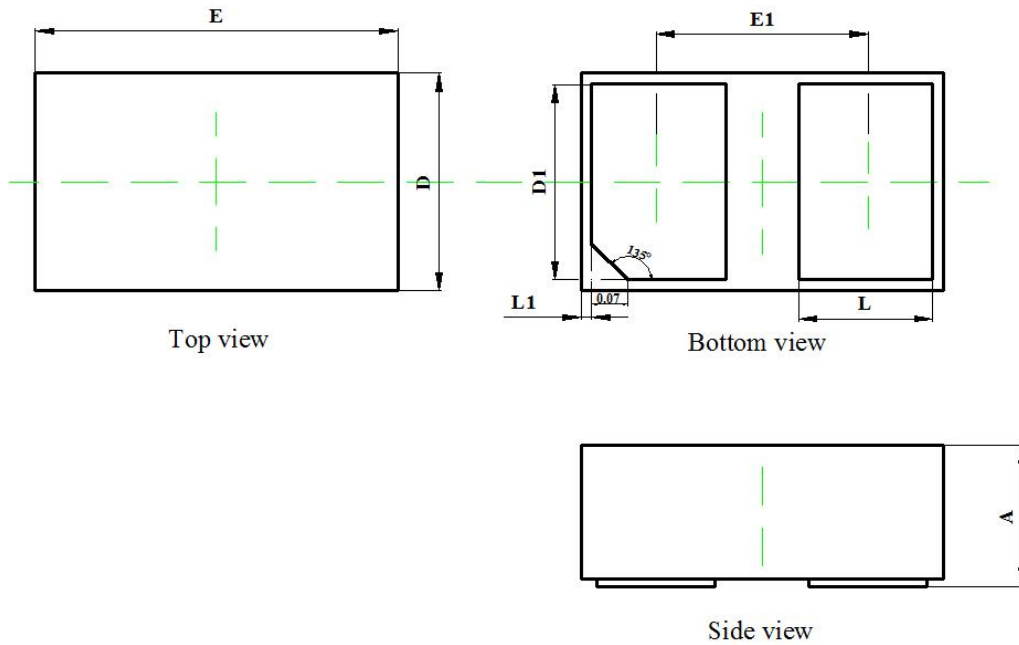


Fig.4 IV Curve

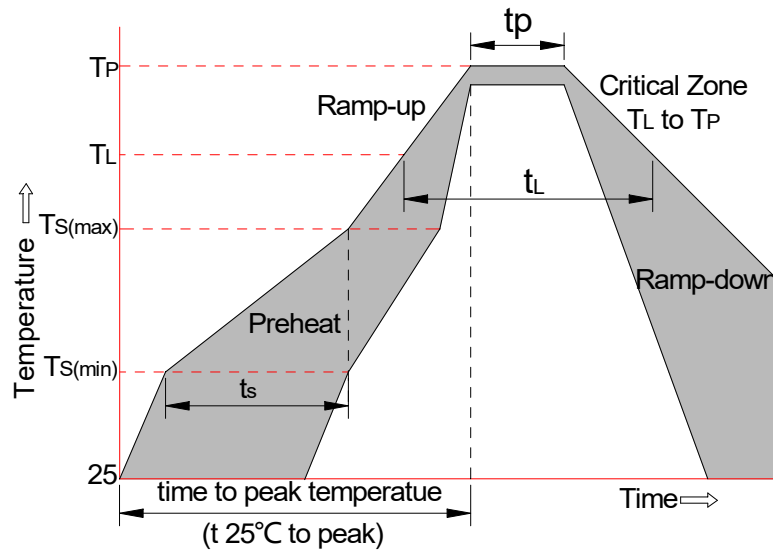
## 9. Package Dimension

DFN1006 Package Outline



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
<b>A</b>	0.320	0.420	0.013	0.017
<b>D</b>	0.550	0.650	0.022	0.026
<b>E</b>	0.950	1.050	0.037	0.041
<b>D1</b>	0.450	0.550	0.018	0.022
<b>E1</b>	0.550	0.650	0.022	0.026
<b>L</b>	0.280	0.380	0.011	0.015
<b>L1</b>	0.000	0.100	0.000	0.004

## 10. Soldering Parameters



Reflow Condition		Pb-Free Assembly
Pre-heat	-Temperature Min ( $T_{s(min)}$ )	+150°C
	-Temperature Max( $T_{s(max)}$ )	+200°C
	-Time (Min to Max) ( $t_s$ )	60-180 secs.
Average ramp up rate (Liquid us Temp ( $T_L$ ) to peak)		3°C/sec. Max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature( $T_L$ )(Liquid us)	+217°C
	-Temperature( $t_L$ )	60-150 secs.
Peak Temp ( $T_p$ )		+260(+0/-5)°C
Time within 5°C of actual Peak Temp ( $t_p$ )		30 secs. Max
Ramp-down Rate		6°C/sec. Max
xTime 25°C to Peak Temp ( $T_p$ )		8 min. Max
Do not exceed		+260°C